Chip Scale Review

2018 Editorial Calendar

(Editorial close date: 11/20/2017

January • February

* indicates show distribution

Topics	Shows
Enabling advanced applications in semiconductor packaging	• **SEMI European 3D Summit** Dresden, Germany (Jan 22-24)
Challenges and solutions to driving fan-out into high volume	• **SEMICON Korea** Seoul, Korea (Jan 31-Feb 2)
Surface analysis as a blueprint for semiconductor package manufacturing	• **SMTA Pan Pac Microelectronics Symposium** Waimea, Hawaii (Feb 5-8)
Laser debonding for WLP	• **2018 FLEX** Monterey, CA (Feb 12-15)
Adhesives for advanced packages	• **APEX Expo** San Diego, CA (Feb 27-Mar1)
Automotive sensing	• **ISS Europe** Dublin, Ireland, (Mar 4-6)
3D heterogeneous integration	• **BiTS Workshop*** Mesa, AZ (March 4-7)
3D bump inspection	• **IMAPS DPC*** Fountain Hills, AZ (March 5-8)
Improving efficiency in IC testing	• **SEMICON China*** Shanghai, China (March 14-16)
Reliability and thermal management	

Ad Space Close Jan 5 - Ad Materials Close Jan 12

(Editorial close date: 1/6)

March • April

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Topics	Shows
Fan-out for RDL first process	• **SEMICON SE Asia** Kuala Lumpur, Malaysia (May 8-10)
Fan-out wafer and panel technology for LEDs	• **MEMS & Sensors Technical Congress** Stanford, CA (May 10-11)
Package connectivity for HDAP	• **ECTC *** San Diego, CA (May 30- June 2)
Failure analysis for 3D technologies	
Smart innovations in automotive electronics	
Material supply challenges for future devices	
Transfer of WLP to PLP	
Biodegradable and recyclable materials	
Higher performance test solutions	

Ad Space Close Mar 2 - Materials Close Mar 9

(Editorial close date: 3/9)

May • June

* indicates show distribution

Topics	Shows
Next-gen IOT solutions	• **IEEE/SW Test Workshop (SWTW)** San Diego, CA (June 3-6)
Underfill and encapsulation	• **Sensors Expo** San Jose, CA (June 26-28)
Die attach	• **SEMICON West *** San Francisco, CA (July 10-12)
TSVs	
Metrology for stress analysis	
Smart burn-in & test sockets	
Advanced interconnect and bonding technologies for heterogeneous integration	
Trends in Cu pillar	
MEMS and sensors	

Ad Space Close May 4 - Ad Materials Close May 11

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